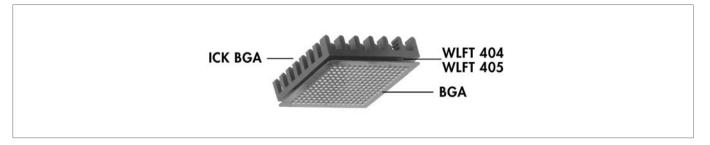
B

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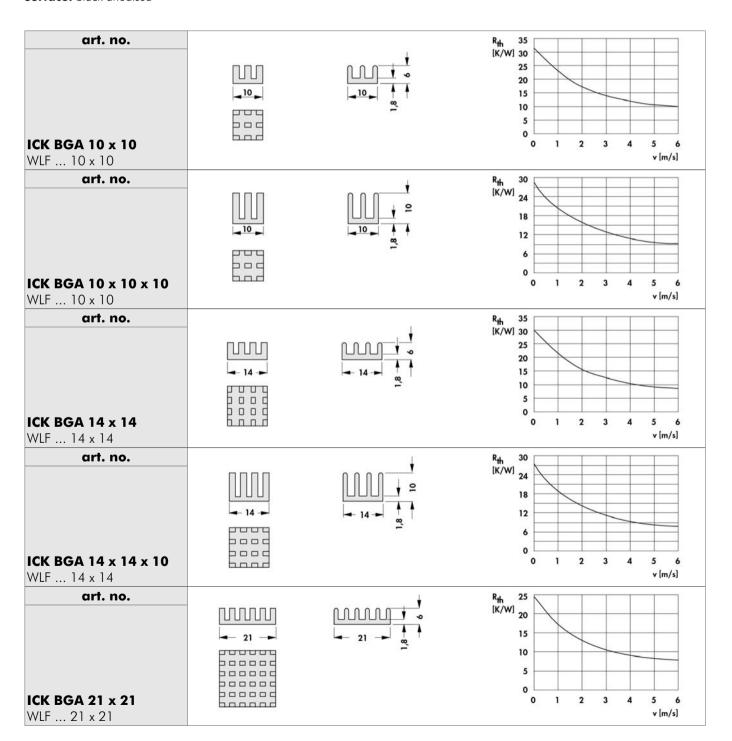
G

Heatsinks for BGAs



- particularly suited for **B**all **G**rid **A**rrays
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component

surface: black anodised



fischer elektronik 23

Heatsinks for BGAs

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art. no.		2	P. 25
ICK BGA 23 x 23 WLF 23 x 23	23 -	23 - 23	R _{th} 25 [K/W] 20 15 10 5 0 0 1 2 3 4 5 6 v [m/s]
art. no. ICK BGA 23 x 23 x 10 WLF 23 x 23	23 -	23 - 23	R _{th} 24 [K/W] 18 12 6 0 0 1 2 3 4 5 6 v [m/s]
art. no. ICK BGA 27 x 27 WLF 27 x 27	27	27 - 27	R _{th} 25 [K/W] 20 15 10 5 0 1 2 3 4 5 6 v [m/s]
art. no. ICK BGA 27 x 27 x 10 WLF 27 x 27	27 -	27 - 27	R _{th} 20 [K/W] 16 12 8 4 0 0 1 2 3 4 5 6 v [m/s]
art. no. ICK BGA 27 x 27 x 14 WLF 27 x 27	27	27 - \$\frac{1}{2}\$	R _{th} 14 (K/W) 12 10 8 6 4 2 0 0 1 2 3 4 5 6 v [m/s]
art. no. ICK BGA 27 x 27 x 22 WLF 27 x 27	27 —>	27	R _{th} 14 [K/W] 12 10 8 6 4 2 2 0 0 1 2 3 4 5 6 v [m/s]



Heatsinks for BGAs

and no			
art. no.	mmm		R _{th} 20 [K/W] 16
	31	31 - 0	12
	0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	-	8
			4
ICK BGA 31 x 31			0 1 2 3 4 5 6
WLF 31 x 31			v [m/s]
art. no.	00000000	• • • • • • • • •	R _{th} 20 [K/W] 16
		<u> </u>	[K/W] 16
	31 —	31 — 4	12
	20000000	557	8
	00000000		0
ICK BGA 31 x 31 x 10	00000000		0 1 2 3 4 5 6 v[m/s]
WLF 31 x 31 art. no.	hononond	7	34 3054
dii. iiv.			R _{th} 20 [K/W] 16
	35	35 — 4	12
	000000000	<u> </u>	8
			4
ICK BGA 35 x 35			0 1 2 3 4 5 6
WLF 35 x 35			v [m/s]
art. no.		00000000	R _{th} 20 [K/W] 16
	35	□□□□□□□□	
	boooooood	8,1	12
	50000000d		4
	200000000		0
ICK BGA 35 x 35 x 10 WLF 35 x 35	200000000		0 1 2 3 4 5 6 v[m/s]
art. no.		.1	R _{th} 20
	<u>mmmmm</u>		[K/W] 16
	37	37 —	12
			8
			4
ICK BGA 37 x 37 x 6			0 1 2 3 4 5 6
WLF 37 x 37	hannanad		v [m/s]
art. no.			R _{th} 14 [K/W] 12
	37 ─►	37 - 1	10
		8,	8 6
	000000000		4
	000000000		2
ICK BGA 37 v 37 v 10	0000000000		0 1 0 0 1 5 1
ICK BGA 37 x 37 x 10 WLF 37 x 37			0 1 2 3 4 5 6 v[m/s]

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7

SMD-heatsinks → B 38 - 40
Mounting material for semiconduct. → E 37 - 41
Hole pattern → A 21
Technical introduction → A 2 - 7

B 18

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